



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD110-B1-02ELS E6327		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001302520						
<b>Package</b>		PG-TSSLP-2-4		<b>Weight*</b>		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.33		3286	
	noble metal	gold	7440-57-5	0.003	1.28		12753	
	inorganic material	silicon	7440-21-3	0.020	9.45	11.06	94492	110531
leadframe	non noble metal	nickel	7440-02-0	0.108	50.94	50.94	509582	509582
wire	noble metal	gold	7440-57-5	0.003	1.24	1.24	12352	12352
encapsulation	organic material	carbon black	1333-86-4	0.000	0.17		1655	
	plastics	epoxy resin	-	0.010	4.80		47960	
	inorganic material	silicondioxide	60676-86-0	0.060	28.11	33.08	281142	330757
leadfinish	noble metal	gold	7440-57-5	0.004	1.74	1.74	17387	17387
plating	noble metal	gold	7440-57-5	0.004	1.94	1.94	19391	19391
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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